



SOT668-2

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 17 leads (row spacing 2.54 mm)

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	RDBS17P
Package type industry code	RDBS17P
Package style descriptive code	RDBS (right-angle DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

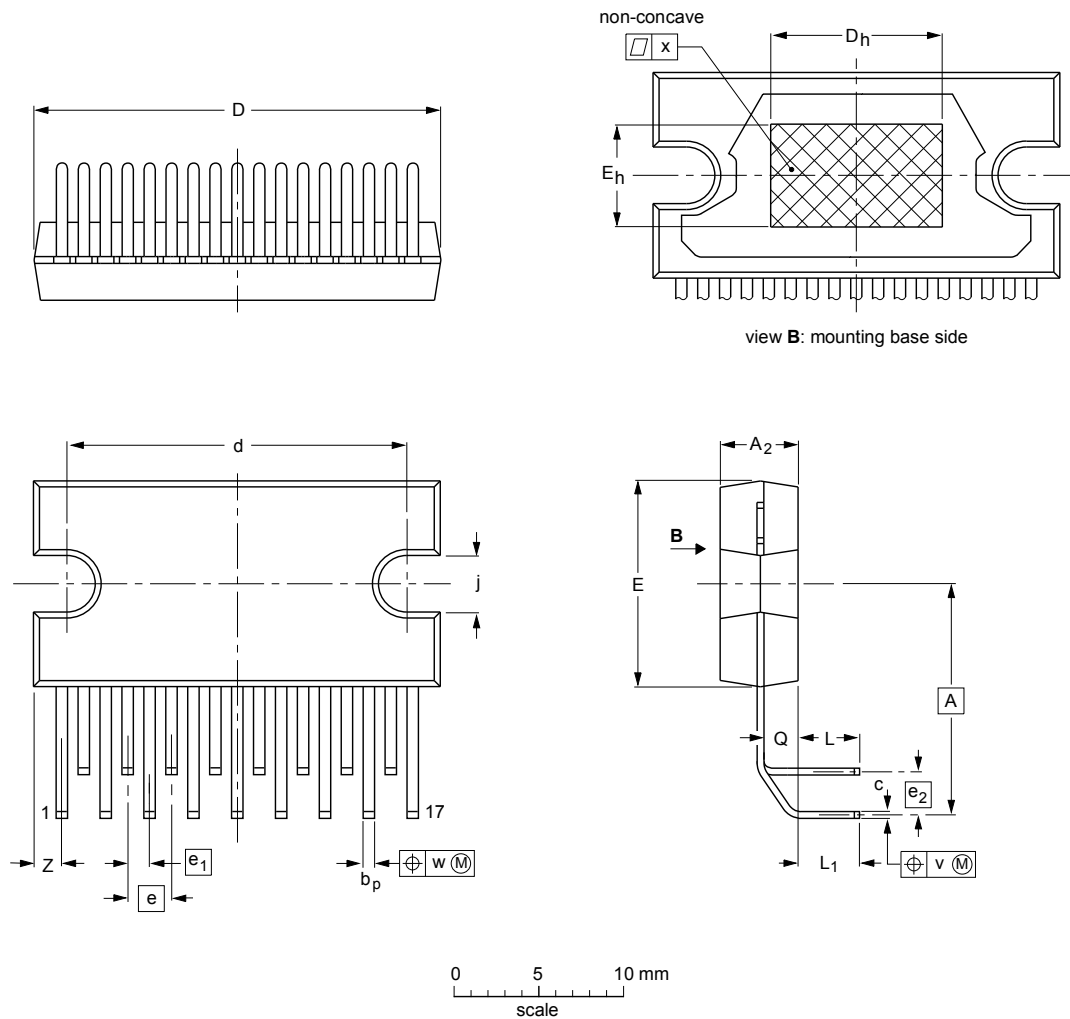
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		23.6	-	23.7	24	mm
E	package width		11.8	-	12	12.2	mm
A ₂	package height		4.4	-	4.4	4.6	mm
n ₂	actual quantity of termination		-	-	17	-	



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2. Package outline

RDBS17P: plastic rectangular-DIL-bent-SIL (reverse bent) power package; 17 leads (row spacing 2.54 mm) SOT668-2



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	e ₂	E _h	j	L	L ₁	Q	v	w	x	Z ⁽¹⁾
mm	13.5	4.6 4.4	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	2.54	1.27	2.54	6	3.4 3.1	3.75 3.15	3.75 3.15	2.1 1.9	0.6	0.4	0.03	2.00 1.45

Note
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT668-2						01-01-05 03-03-12

Fig. 1. Package outline RDBS17P (SOT668-2)

3. Legal information

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